E	2016-3				
F	2018-12-14	2	t		

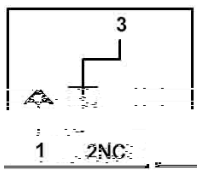
/ Descriptions

SOT-23

/ Features

/ Applications

/ Equivalent Circuit



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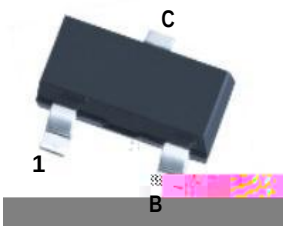
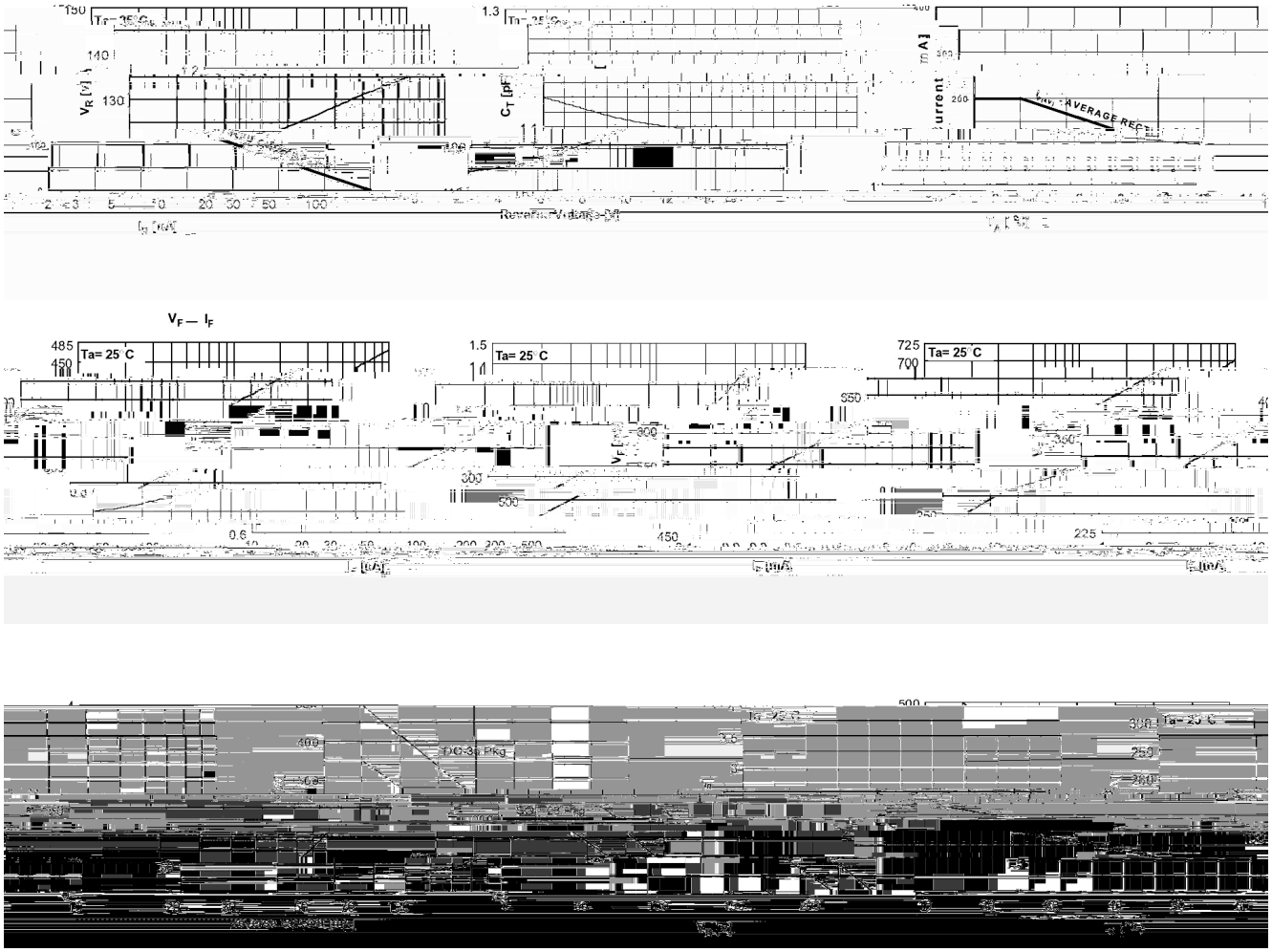
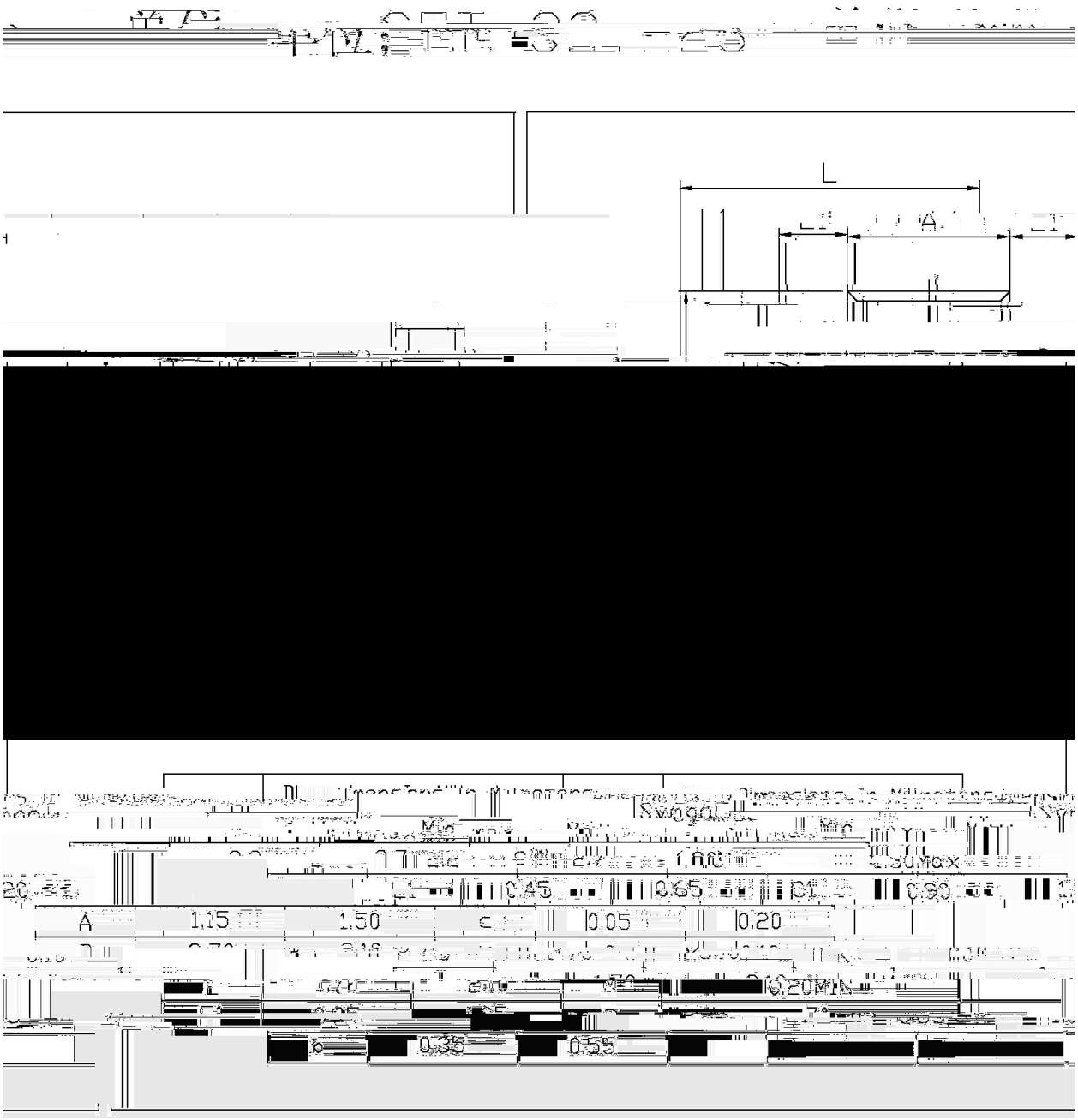


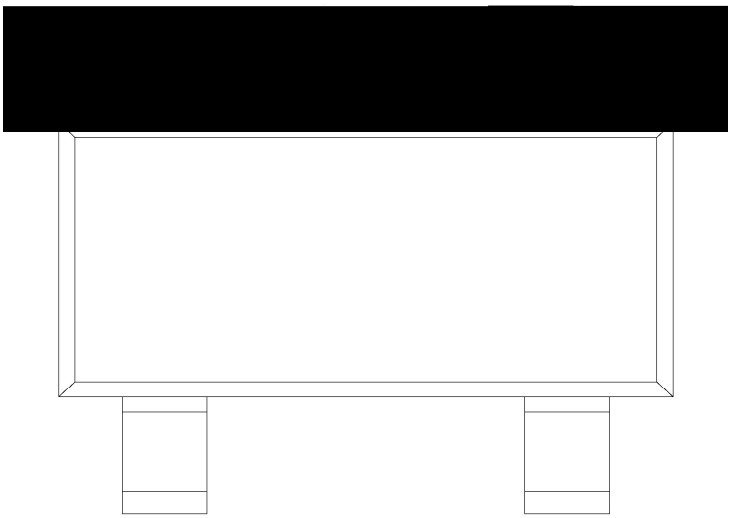
/ h_{FE} Classifications & Marking

/ Electrical Characteristic Curve

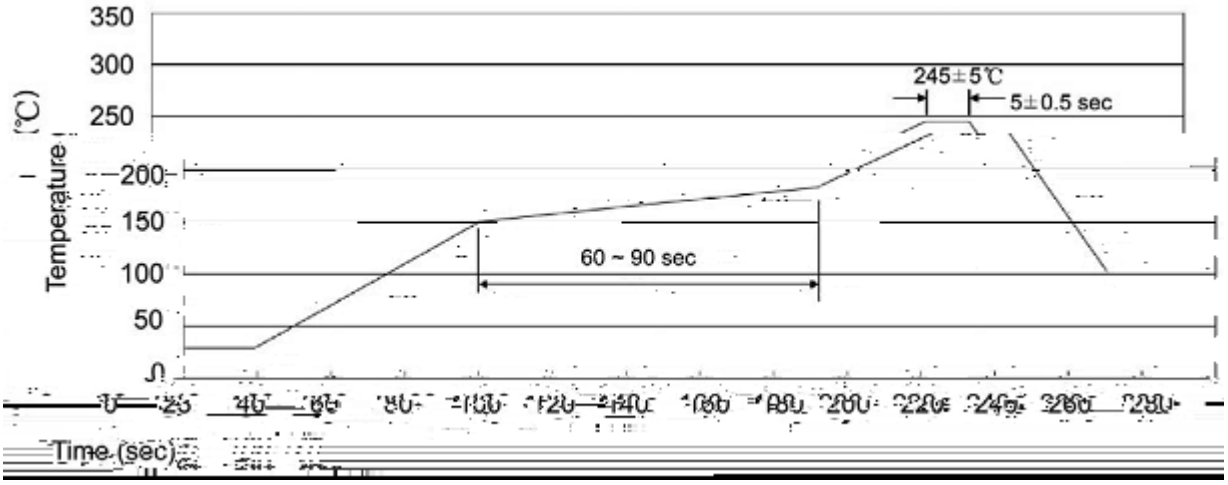


/ Package Dimensions





( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



± ± ± ±

/ Resistance to Soldering Heat Test Conditions

± ± ℃

/ Packaging SPEC.

!	" # $					" % & '		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box (	Outer Box)
SOT-23	3,000	10	30,000	8	240,000	7″ ×8	180×120×180	385×257×392

/ Notices